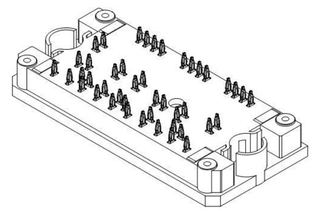
Q1 3-Phase TNPC Module

NXH40T120L3Q1

The NXH40T120L2Q1 is a power module containing a three channel T−type neutral−point clamped (TNPC) circuit. Each channel has two 1200 V, 40 A IGBTs with inverse diodes and two 650 V, 25 A IGBTs with inverse diodes. The module contains an NTC thermistor.



Q1 3−TNPC
CASE 180AS
Solder pins follow similar pattern

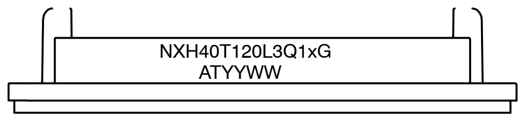
Features

- Low Package Height
- Compact 82.5 mm x 37.4 mm x 12 mm Package
- Options with Press−fit Pins and Solder Pins
- Options with Pre−applied Thermal Interface Material (TIM) and without Pre−applied TIM
- Thermistor
- This Device is Pb−Free and is RoHS Compliant

Applications

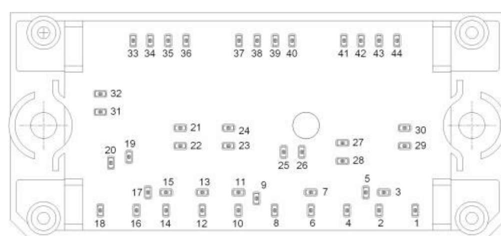
- Solar Inverters
- UPS
- Energy Storage Systems

MARKING DIAGRAM



NXH40T120L3Q1x	= Device Code
A	= Assembly Site Code
T	= Test Site Code
YYWW	= Year and Work Week Code
G	= Pb−Free Package

PIN CONNECTIONS



ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

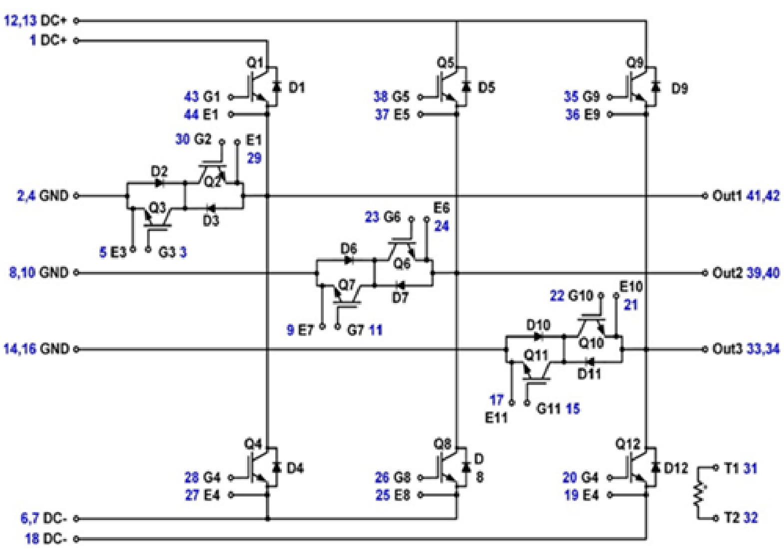


Figure 1. NXH40T120L3Q1 Schematic Diagram

MAXIMUM RATINGS (Note 1)

Rating	Symbol	Value	Unit
IGBT (Q1, Q4, Q5, Q8, Q9, Q12)			
Collector – Emitter Voltage	V_{CES}	1200	V
Gate – Emitter Voltage	V_{GE}	±20	V
Continuous Collector Current @ T_C = 80°C (T_J = 175°C)	I_C	40	A
Pulsed Collector Current (T_J = 175°C)	I_{Cpulse}	120	A
Maximum Power Dissipation (T_J = 175°C)	P_{tot}	145	W
Minimum Operating Junction Temperature	T_{JMIN}	–40	°C
Maximum Operating Junction Temperature	T_{JMAX}	175	°C
DIODE (D1, D4, D5, D8, D9, D12)			
Peak Repetitive Reverse Voltage	V_{RRM}	1200	V
Continuous Forward Current @ T_C = 80°C (T_J = 175°C)	I_F	25	A
Repetitive Peak Forward Current (T_J = 175°C)	I_{FRM}	75	A
Maximum Power Dissipation (T_J = 175°C)	P_{tot}	55	W
Minimum Operating Junction Temperature	T_{JMIN}	– 40	°C
Maximum Operating Junction Temperature	T_{JMAX}	175	°C
IGBT+DIODE (Q2+D2, Q3+D3, Q6+D6, Q7+D7, Q10+D10, Q11+D11)			
Collector – Emitter Voltage	V_{CES}	650	V
Gate – Emitter Voltage	V_{GE}	±20	V
Continuous Collector Current @ T_C = 80°C (T_J = 175°C)	I_C	42	A
Pulsed Collector Current (T_J = 175°C)	I_{Cpulse}	126	A
Maximum Power Dissipation (T_J = 175°C)	P_{tot}	146	W
Minimum Operating Junction Temperature	T_{JMIN}	–40	°C
Maximum Operating Junction Temperature	T_{JMAX}	175	°C
THERMAL PROPERTIES			
Storage Temperature range	T_{stg}	– 40 to 150	°C
INSULATION PROPERTIES			
Isolation Test Voltage, t = 1 sec, 60 Hz	V_{is}	3000	V_{RMS}
Creepage Distance		12.7	mm

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Refer to ELECTRICAL CHARACTERISTICS, RECOMMENDED OPERATING RANGES and/or APPLICATION INFORMATION for Safe Operating parameters.

RECOMMENDED OPERATING CONDITIONS

Rating	Symbol	Min	Max	Unit
Module Operating Junction Temperature	T_J	–40	150	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

ELECTRICAL CHARACTERISTICS (T_J = 25°C Unless Otherwise Noted)

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Unit
IGBT CHARACTERISTICS (Q1, Q4, Q5, Q8, Q9, Q12)						
Collector–Emitter Cutoff Current	V_{GE} = 0 V, V_{CE} = 1200 V	ICES	–	–	400	μA
Collector–Emitter Saturation Voltage	V_{GE} = 15 V, I_C = 40 A, T_J = 25°C	VCE(sat)	–	1.85	2.20	V
	V_{GE} = 15 V, I_C = 40 A , T_J = 150°C		–	2.25	–	
Gate–Emitter Threshold Voltage	V_{GE} = V_{CE}, I_C = 1.5 mA	VGE(TH)	4.50	–	6.50	V
Gate Leakage Current	V_{GE} = 20 V, V_{CE} = 0 V	IGES	–	–	800	nA
Turn–on Delay Time	T_J = 25°C V_{CE} = 350 V, I_C = 28 A, V_{GE} = ±15 V, R_G = 8 Ω	td(on)	–	63	–	ns
Rise Time		t_r	–	22	–	
Turn–off Delay Time		td(off)	–	199	–	
Fall Time		t_f	–	23	–	
Turn–on Switching Loss per Pulse		Eon	–	560	–	μJ
Turn off Switching Loss per Pulse		Eoff	–	338	–	
Turn–on Delay Time	T_J = 125°C V_{CE} = 350 V, I_C = 28 A, V_{GE} = ±15 V, R_G = 8 Ω	td(on)	–	59	–	ns
Rise Time		t_r	–	24	–	
Turn–off Delay Time		td(off)	–	225	–	
Fall Time		t_f	–	80	–	
Turn – on Switching Loss per Pulse		Eon	–	757	–	μJ
Turn off Switching Loss per Pulse		Eoff	–	910	–	
Input Capacitance	V_{CE} = 20 V V_{GE} = 0 V, f = 1 MHz	Cies	–	7753	–	pF
Output Capacitance		Coes	–	227	–	
Reverse Transfer Capacitance		Cres	–	127	–	
Total Gate Charge	V_{CE} = 350 V, I_C = 40 A, V_{GE} = ±15 V	Q_g	–	536	–	nC
Thermal Resistance – chip–to–heatsink	Thermal grease, Thickness ≤ 2.25 Mil, λ = 2.9 W/mK	RthJH	–	1.01	–	°C/W
DIODE CHARACTERISTICS (D1, D4, D5, D8, D9, D12)						
Diode Forward Voltage	I_F = 20 A, T_J = 25°C	V_F	–	2.4	2.7	V
	I_F = 20 A, T_J = 150°C		–	1.7	–	
Reverse Recovery Time	T_J = 25°C V_{CE} = 350 V, I_C = 28 A, V_{GE} = ±15 V, R_G = 16 Ω	trr	–	43	–	ns
Reverse Recovery Charge		Qrr	–	756	–	μC
Peak Reverse Recovery Current		IRRM	–	35	–	A
Peak Rate of Fall of Recovery Current		di/dt	–	750	–	A/μs
Reverse Recovery Energy		Err	–	104	–	μJ
Reverse Recovery Time	T_J = 125°C V_{CE} = 350 V, I_C = 28 A, V_{GE} = ±15 V, R_G = 16 Ω	trr	–	129	–	ns
Reverse Recovery Charge		Qrr	–	2702	–	μC
Peak Reverse Recovery Current		IRRM	–	45	–	A
Peak Rate of Fall of Recovery Current		di/dt	–	407	–	A/μs
Reverse Recovery Energy		Err	–	428	–	μJ
Thermal Resistance – chip–to–heatsink	Thermal grease, Thickness ≤ 2.25 Mil, λ = 2.9 W/mK	RthJH	–	1.63	–	°C/W

ELECTRICAL CHARACTERISTICS (T_J = 25°C Unless Otherwise Noted) (continued)

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Unit
IGBT CHARACTERISTICS (Q2, Q3, Q6, Q7, Q10, Q11)						
Collector−Emitter Cutoff Current	V_{GE} = 0 V, V_{CE} = 650 V	I_{CES}	–	–	250	µA
Collector−Emitter Saturation Voltage	V_{GE} = 15 V, I_C = 50 A, T_J = 25°C	$V_{CE(sat)}$	–	1.50	–	V
	V_{GE} = 15 V, I_C = 50 A , T_J = 150°C		–	1.53	–	
Gate−Emitter Threshold Voltage	V_{GE} = V_{CE}, I_C = 1.65 mA	$V_{GE(TH)}$	2.60	4.40	6.40	V
Gate Leakage Current	V_{GE} = 20 V, V_{CE} = 0 V	I_{GES}	–	–	400	nA
Turn−on Delay Time	T_J = 25°C V_{CE} = 350 V, I_C = 28 A, V_{GE} = ±15 V, R_G = 16 Ω	$t_{d(on)}$	–	54	–	ns
Rise Time		t_r	–	15	–	
Turn−off Delay Time		$t_{d(off)}$	–	157	–	
Fall Time		t_f	–	12	–	
Turn−on Switching Loss per Pulse		E_{on}	–	416	–	µJ
Turn off Switching Loss per Pulse		E_{off}	–	321	–	
Turn−on Delay Time	T_J = 125°C V_{CE} = 350 V, I_C = 28 A, V_{GE} = ±15 V, R_G = 16 Ω	$t_{d(on)}$	–	52	–	ns
Rise Time		t_r	–	16	–	
Turn−off Delay Time		$t_{d(off)}$	–	178	–	
Fall Time		t_f	–	18	–	
Turn – on Switching Loss per Pulse		E_{on}	–	671	–	µJ
Turn off Switching Loss per Pulse		E_{off}	–	444	–	
Input Capacitance	V_{CE} = 20 V V_{GE} = 0 V, f = 1 MHz	C_{ies}	–	3137	–	pF
Output Capacitance		C_{oes}	–	146	–	
Reverse Transfer Capacitance		C_{res}	–	17	–	
Total Gate Charge	V_{CE} = 350 V, I_C = 40 A, V_{GE} = ±15 V	Q_g	–	180	–	nC
Thermal Resistance – chip−to−heatsink	Thermal grease, Thickness ≤ 2.25 Mil, λ = 2.9 W/mK	R_{thJH}	–	0.995	–	°C/W
DIODE CHARACTERISTICS (D2, D3, D6, D7, D10, D11)						
Diode Forward Voltage	I_F = 20 A, T_J = 25°C	V_F	–	1.28	–	V
	I_F = 20 A, T_J = 150°C		–	1.18	–	
Combined IGBT + Diode Voltage Drop	I_F = 20 A, T_J = 25°C	V_F	–	3.05	3.4	V
Reverse Recovery Time	T_J = 25°C V_{CE} = 350 V, I_C = 28 A, V_{GE} = ±15 V, R_G = 8 Ω	t_{rr}	–	69	–	ns
Reverse Recovery Charge		Q_{rr}	–	1267	–	µC
Peak Reverse Recovery Current		I_{RRM}	–	41	–	A
Peak Rate of Fall of Recovery Current		di/dt	–	1599	–	A/µs
Reverse Recovery Energy		E_{rr}	–	244	–	µJ
Reverse Recovery Time	T_J = 125°C V_{CE} = 350 V, I_C = 28 A, V_{GE} = ±15 V, R_G = 8 Ω	t_{rr}	–	111	–	ns
Reverse Recovery Charge		Q_{rr}	–	2323	–	µC
Peak Reverse Recovery Current		I_{RRM}	–	40	–	A
Peak Rate of Fall of Recovery Current		di/dt	–	470	–	A/µs
Reverse Recovery Energy		E_{rr}	–	510	–	µJ

ELECTRICAL CHARACTERISTICS (T_J = 25°C Unless Otherwise Noted) (continued)

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Unit
THERMISTOR CHARACTERISTICS						
Nominal resistance	T = 25°C	R25		22		kΩ
Nominal resistance	T = 100°C	R100		1468		Ω
Deviation of R25		R/R	−5		5	%
Power dissipation		P_D		200		mW
Power dissipation constant				2		mW/K
B−value	B(25/50), tolerance ±3%			3950		K
B−value	B(25/100), tolerance ±3%			3998		K

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Orderable Part Number	Marking	Package	Shipping
NXH40T120L3Q1PG	NXH40T120L3Q1PG	Q1 3−Phase TNPC − Case 180AS Press−fit Pins (Pb−Free)	21 Units / Blister Tray
NXH40T120L3Q1SG	NXH40T120L3Q1SG	Q1 3−Phase TNPC − Case 180BN Solder Pins (Pb−Free)	21 Units / Blister Tray
NXH40T120L3Q1PTG	NXH40T120L3Q1PTG	Q1 3−Phase TNPC − Case 180AS Press−fit Pins (Pb−Free)	21 Units / Blister Tray

TYPICAL CHARACTERISTICS – HALF BRIDGE IGBT (Q1, Q4, Q5, Q8, Q9, Q12) AND DIODE (D1, D4, D5, D8, D9, D12)

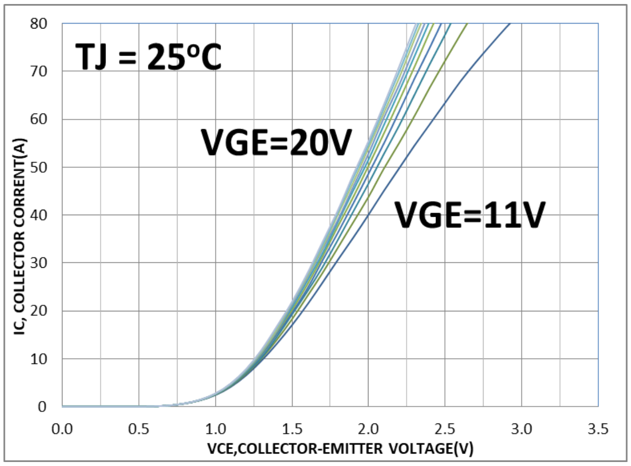


Figure 2. Typical Output Characteristics

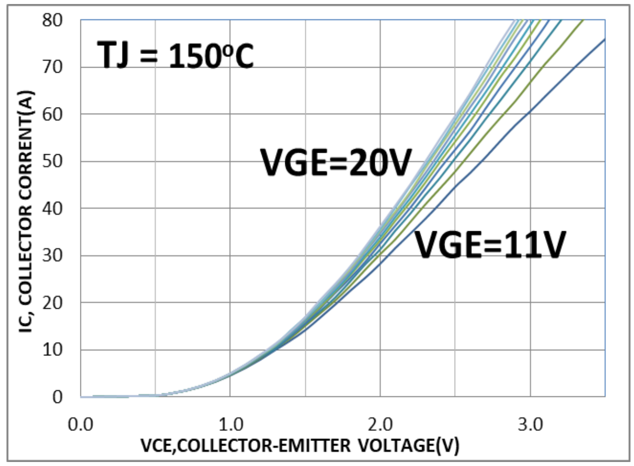


Figure 3. Typical Output Characteristics

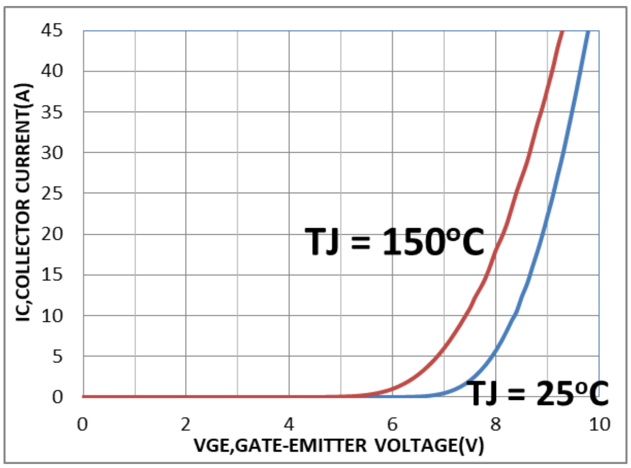


Figure 4. Typical Transfer Characteristics

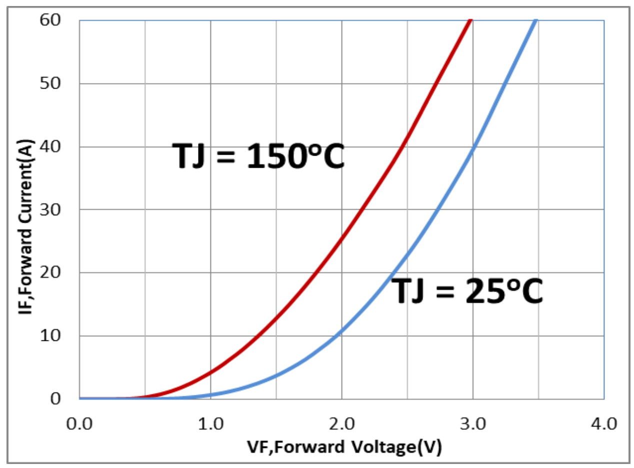


Figure 5. Diode Forward Characteristics

TYPICAL CHARACTERISTICS – HALF BRIDGE IGBT (Q1, Q4, Q5, Q8, Q9, Q12) AND DIODE (D1, D4, D5, D8, D9, D12)

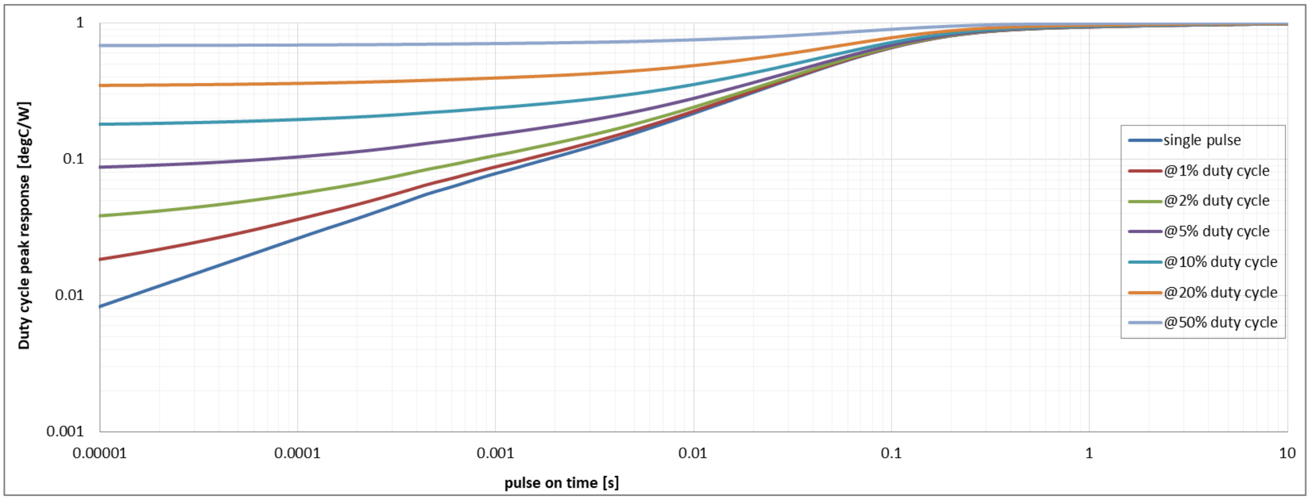


Figure 6. Transient Thermal Impedance (Half Bridge IGBT)

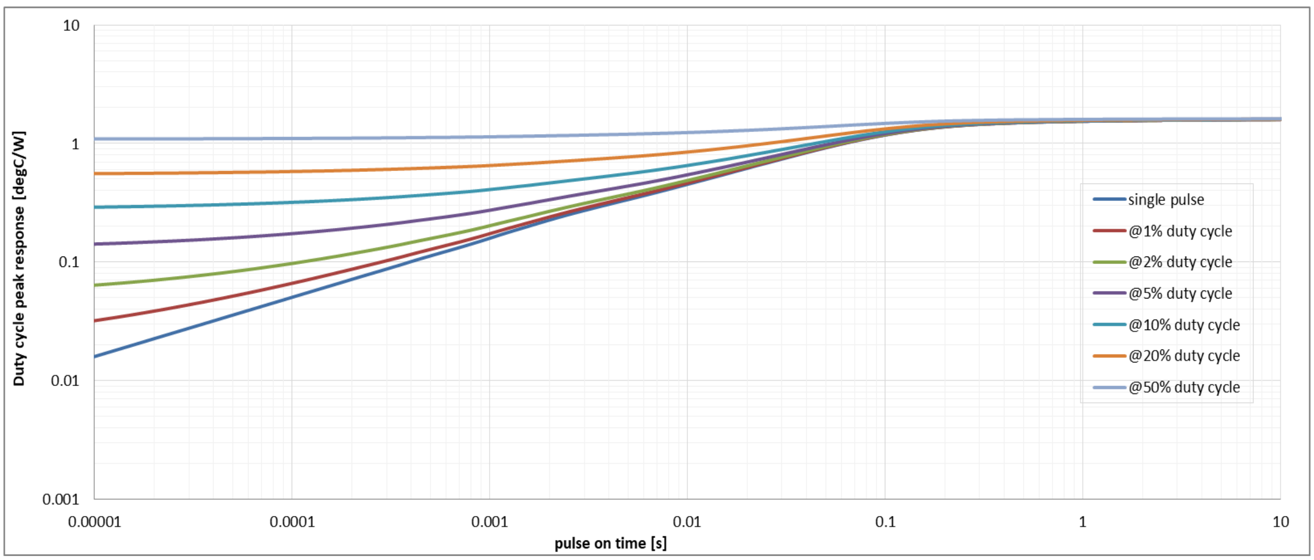


Figure 7. Transient Thermal Impedance (Half Bridge Diode)

TYPICAL CHARACTERISTICS – HALF BRIDGE IGBT (Q1, Q4, Q5, Q8, Q9, Q12) AND DIODE (D1, D4, D5, D8, D9, D12)

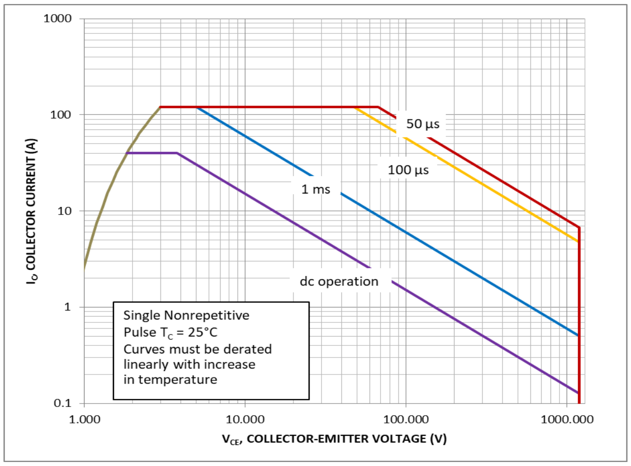


Figure 8. FBSOA

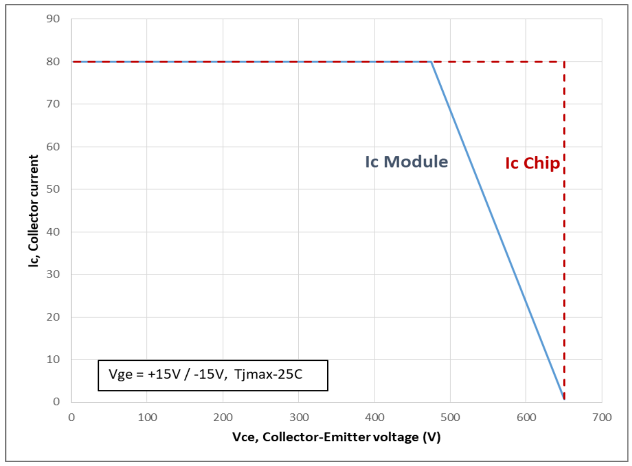


Figure 9. RBSOA

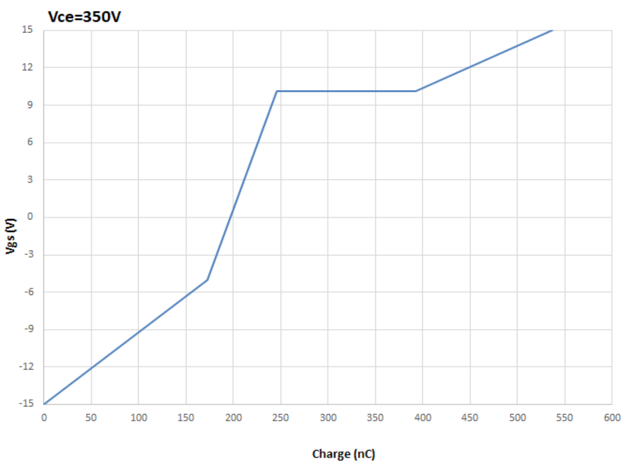


Figure 10. Gate Voltage vs. Gate Charge

TYPICAL CHARACTERISTICS – NP IGBT + DIODE (Q2+D2, Q3+D3, Q6+D6, Q7+D7, Q10+D10, Q11+D11)

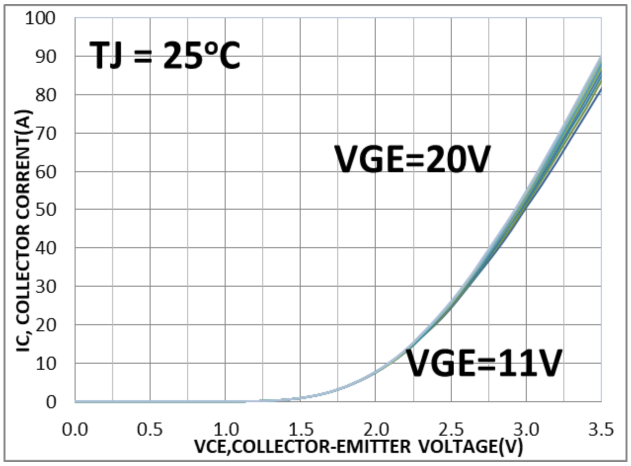


Figure 11. Typical Output Characteristics (I_C versus V_{DT})

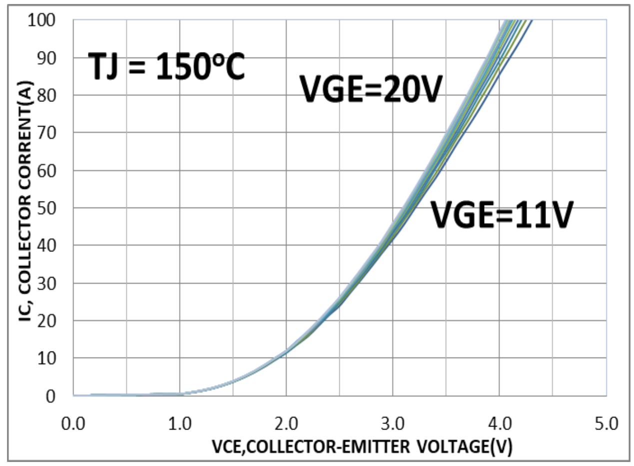


Figure 12. Typical Output Characteristics (I_C versus V_{DT})

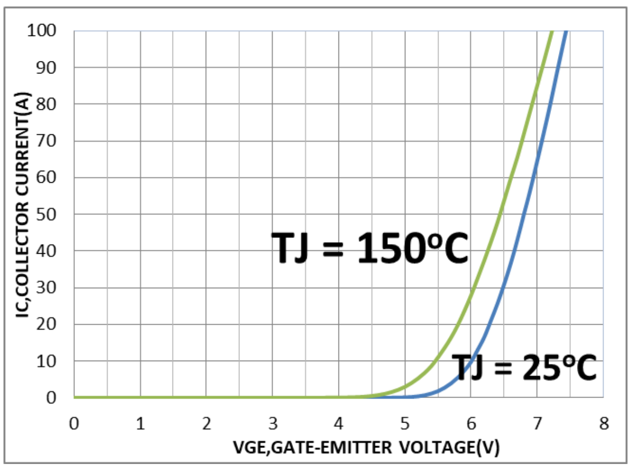


Figure 13. Typical Transfer Characteristics

TYPICAL CHARACTERISTICS – NP IGBT + DIODE (Q2+D2, Q3+D3, Q6+D6, Q7+D7, Q10+D10, Q11+D11)

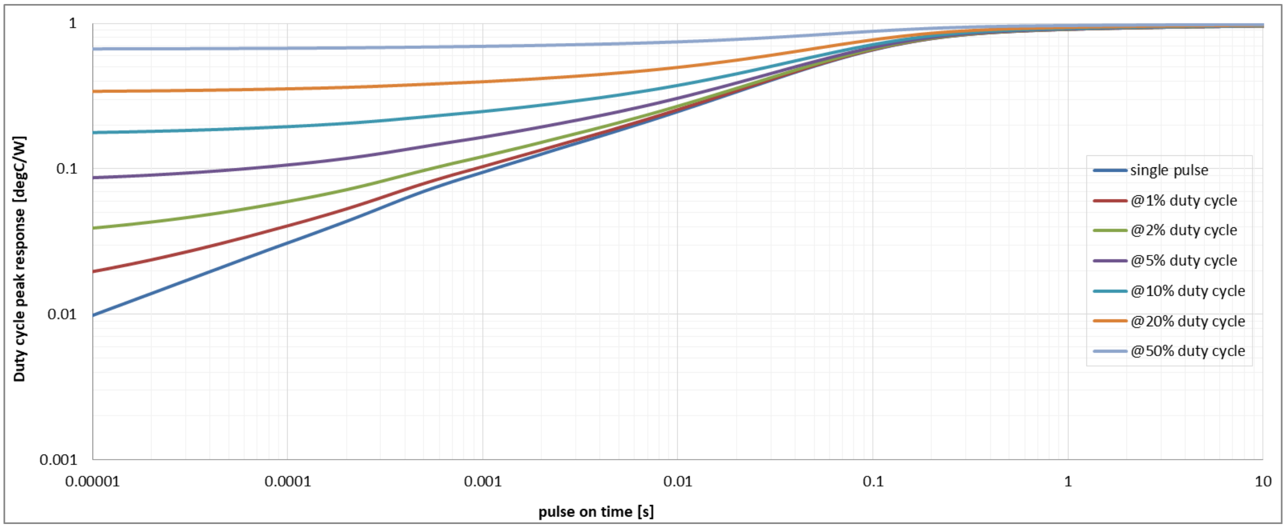


Figure 14. Transient Thermal Impedance (Neutral Point IGBT + Diode)

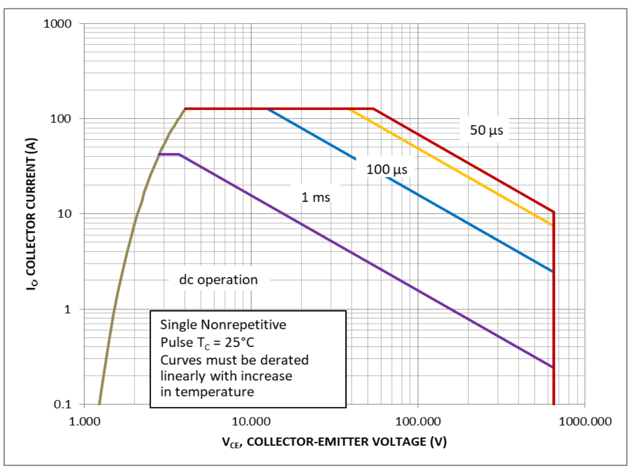


Figure 15. FBSOA (NP IGBT + Diode)

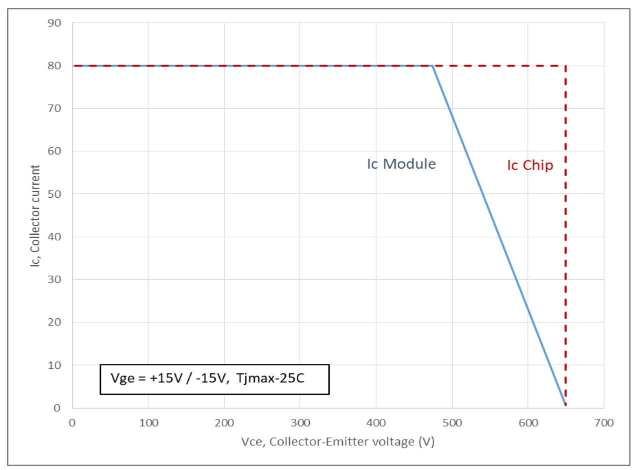


Figure 16. RBSOA (NP IGBT + Diode)

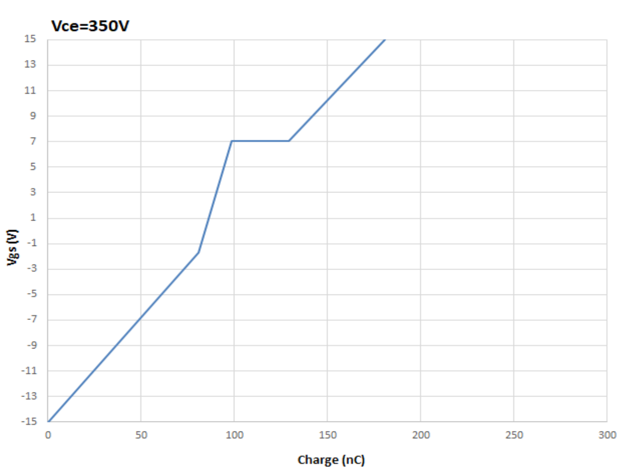


Figure 17. Gate Voltage vs. Gate Charge

TYPICAL CHARACTERISTICS – HALF BRIDGE IGBT COMMUTATES NEUTRAL POINT DIODE

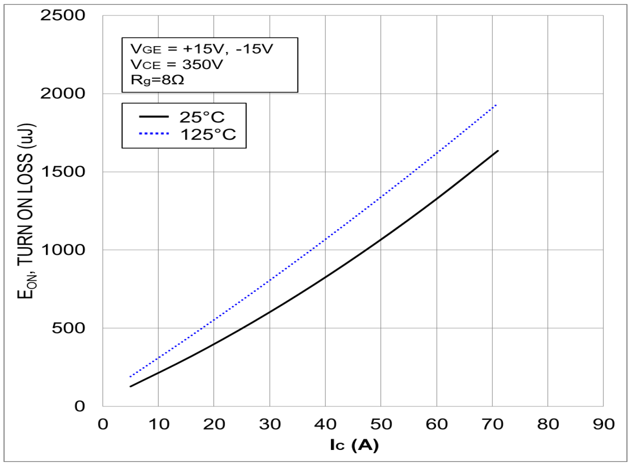


Figure 18. Typical Switching Loss E_{ON} vs. I_C

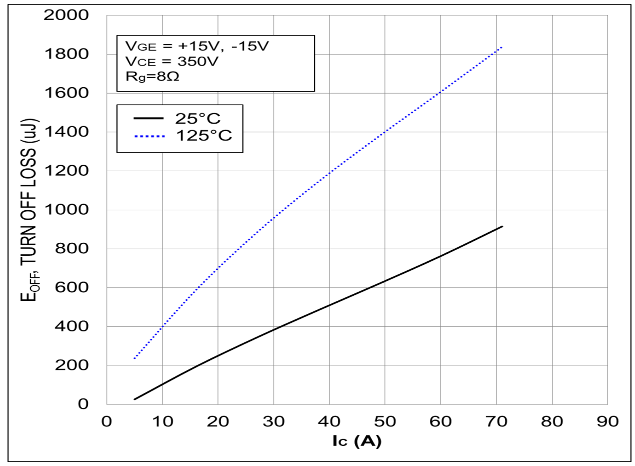


Figure 19. Typical Switching Loss E_{OFF} vs. I_C

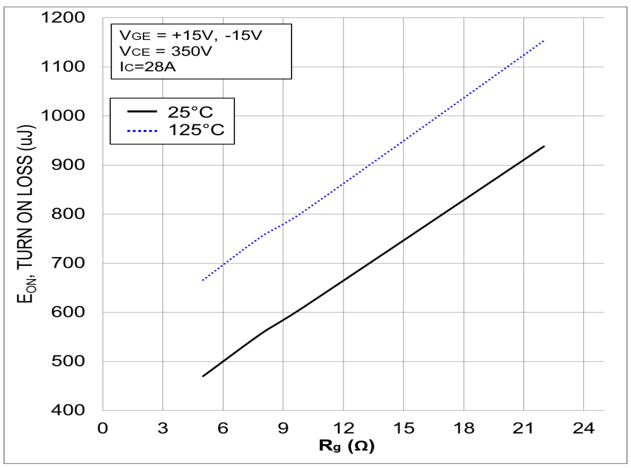


Figure 20. Typical Switching Loss E_{ON} vs. R_G

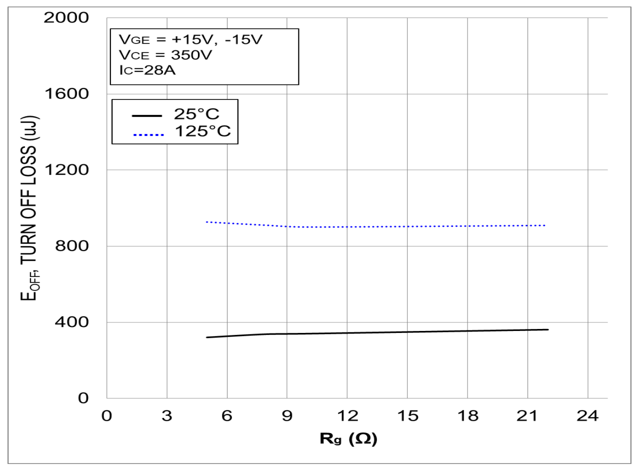


Figure 21. Typical Switching Loss E_{OFF} vs. R_G

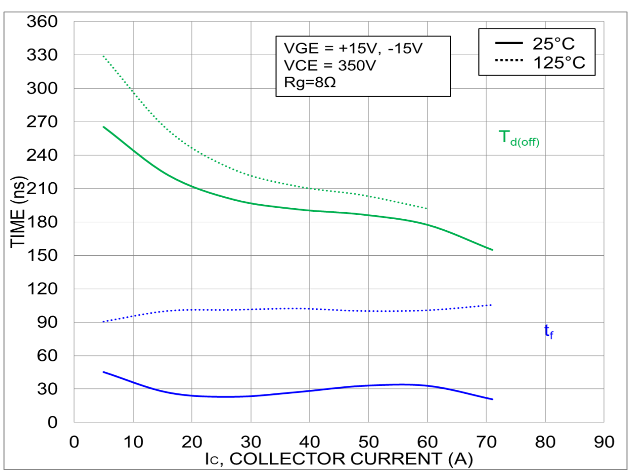


Figure 22. Typical Switching Time T_{DOFF} vs. I_C

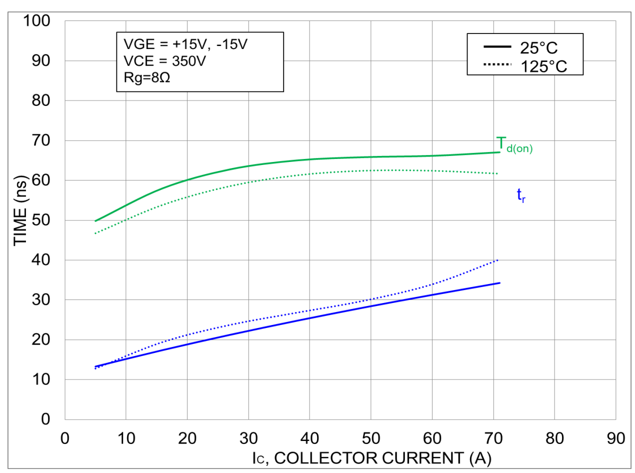


Figure 23. Typical Switching Time T_{DON} vs. I_C

TYPICAL CHARACTERISTICS – HALF BRIDGE IGBT COMMUTATES NEUTRAL POINT DIODE

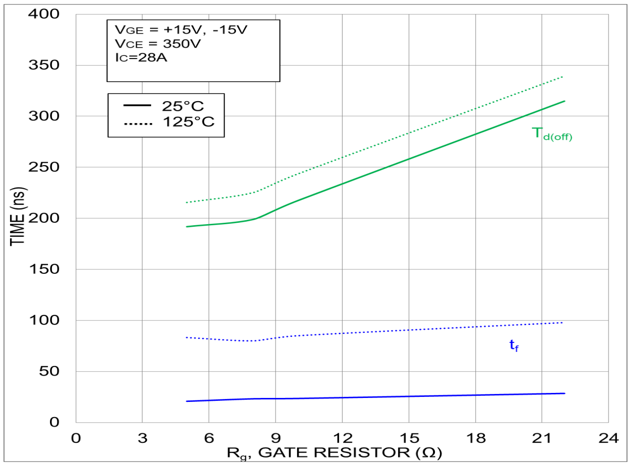


Figure 24. Typical Switching Time T_{DOFF} vs. R_G

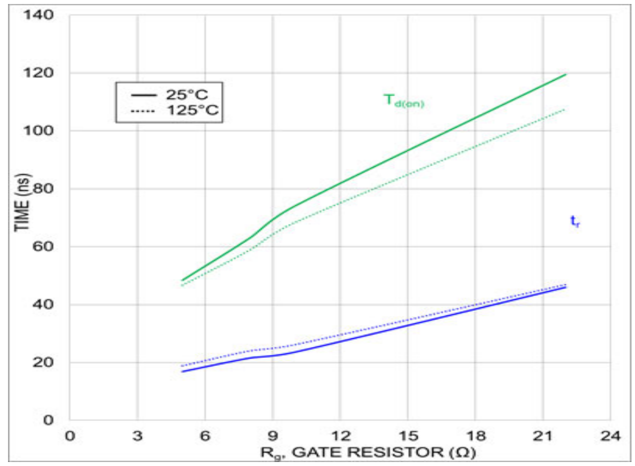


Figure 25. Typical Switching Time T_{DON} vs. R_G

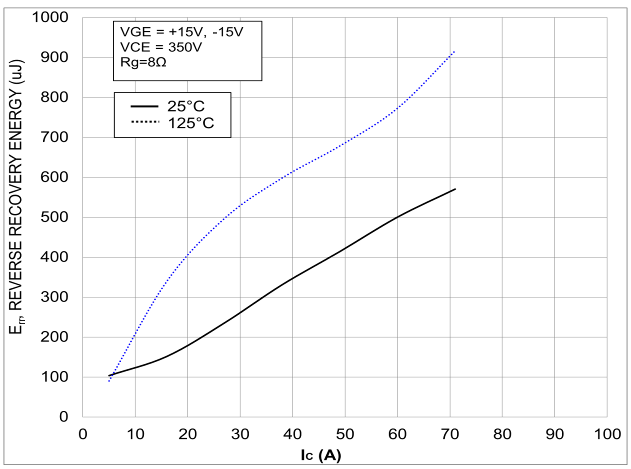


Figure 26. Typical Reverse Recovery Energy Loss vs. I_C

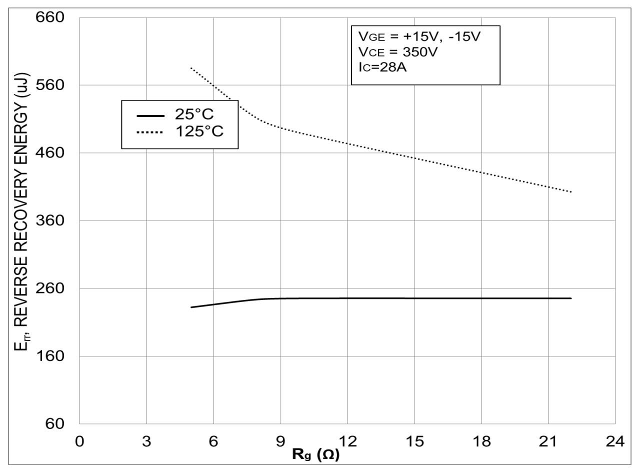


Figure 27. Typical Reverse Recovery Energy Loss vs. R_G

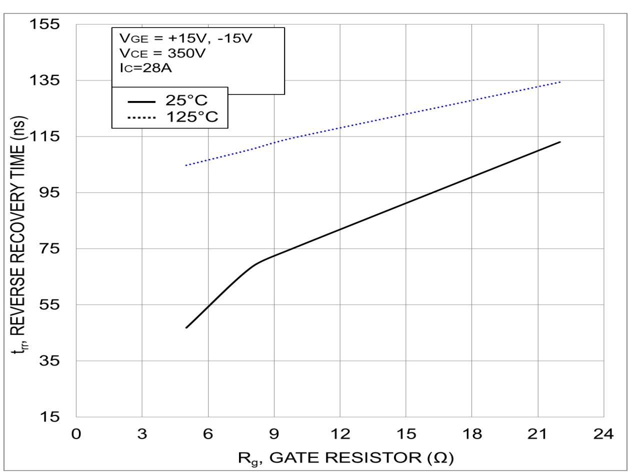


Figure 28. Typical Reverse Recovery Time vs. R_G

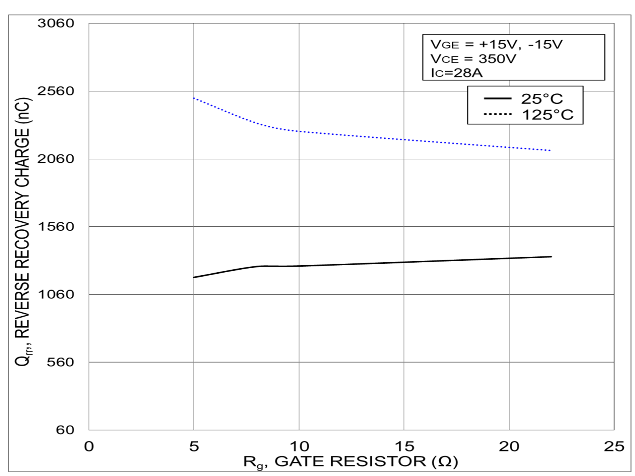


Figure 29. Typical Reverse Recovery Charge vs. R_G

TYPICAL CHARACTERISTICS – HALF BRIDGE IGBT COMMUTATES NEUTRAL POINT DIODE

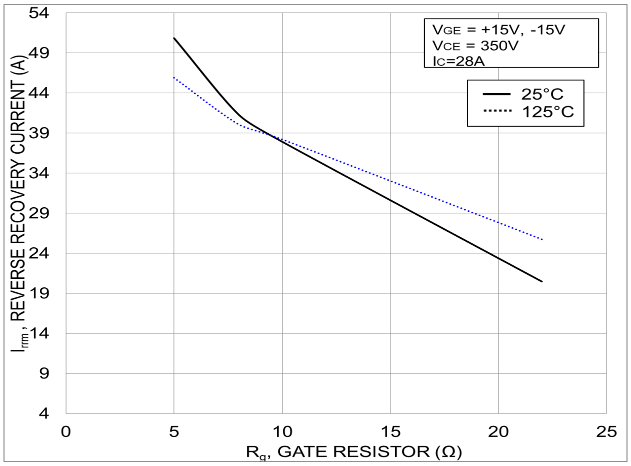


Figure 30. Typical Reverse Recovery Peak Current vs. R_G

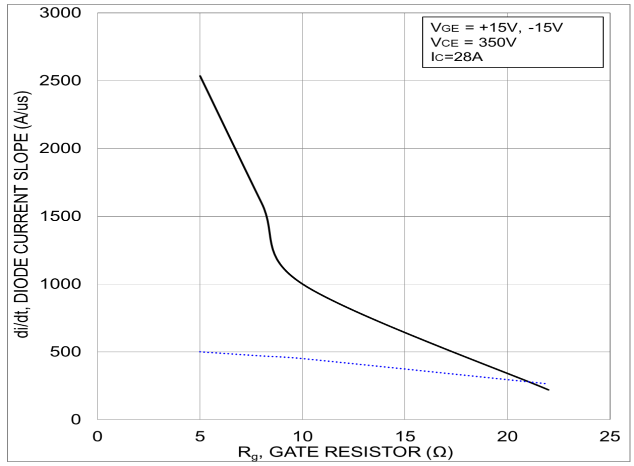


Figure 31. Typical di/dt vs. R_G

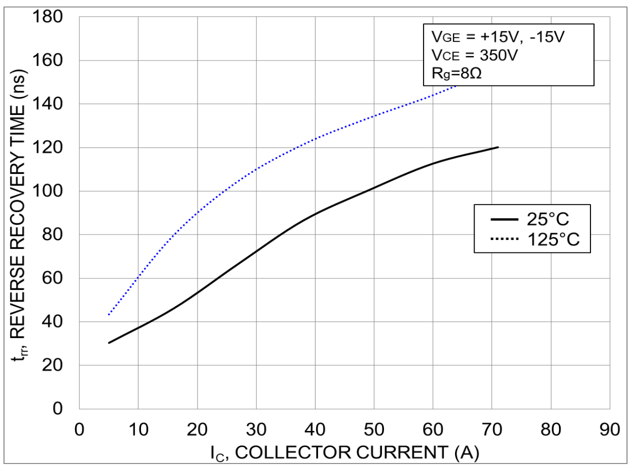


Figure 32. Typical Reverse Recovery Time vs. I_C

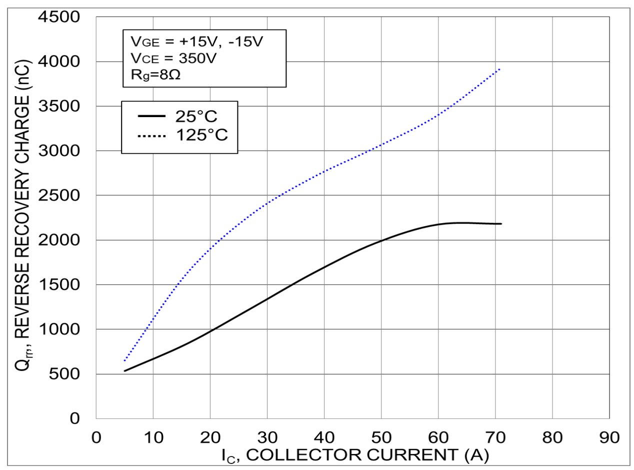


Figure 33. Typical Reverse Recovery Charge vs. I_C

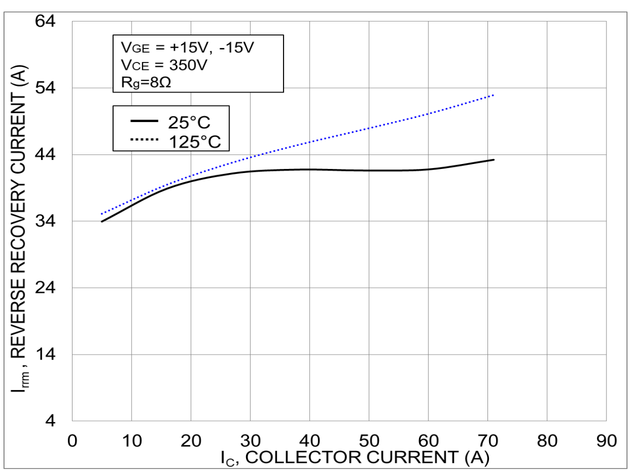


Figure 34. Typical Reverse Recovery Current vs. I_C

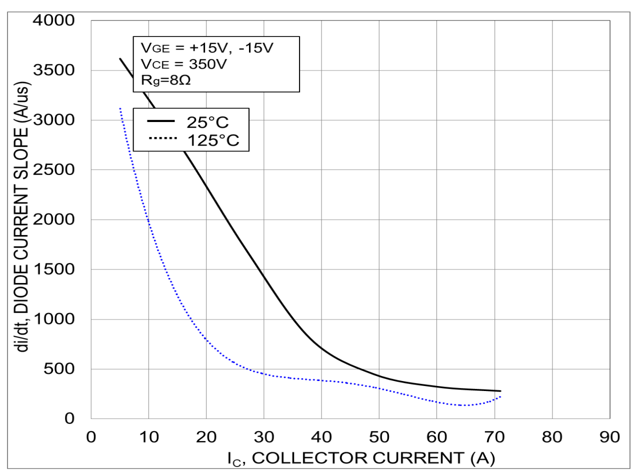


Figure 35. Typical di/dt Current Slope vs. I_C

TYPICAL CHARACTERISTICS – NEUTRAL POINT IGBT COMMUTATES HALF BRIDGE DIODE

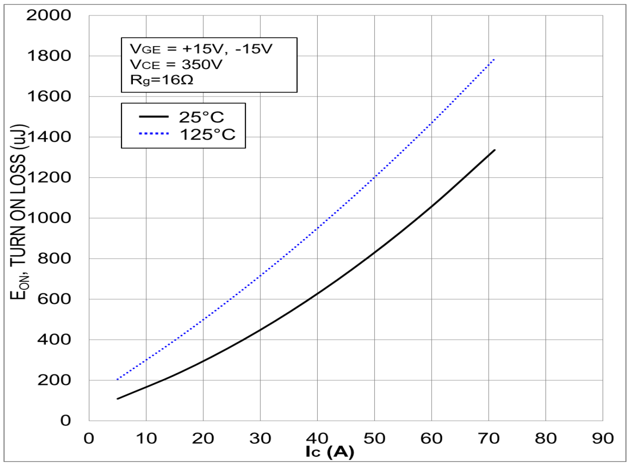


Figure 36. Typical Turn ON Loss vs. I_C

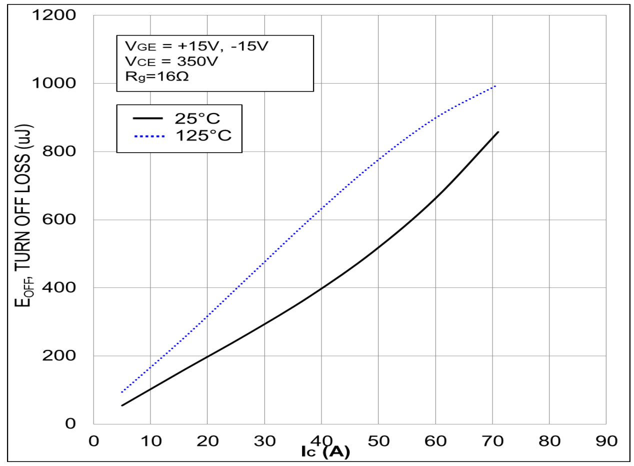


Figure 37. Typical Turn OFF Loss vs. I_C

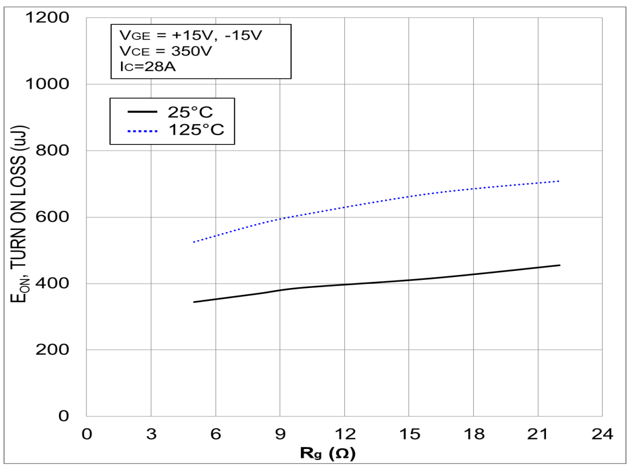


Figure 38. Typical Turn ON Loss vs. R_G

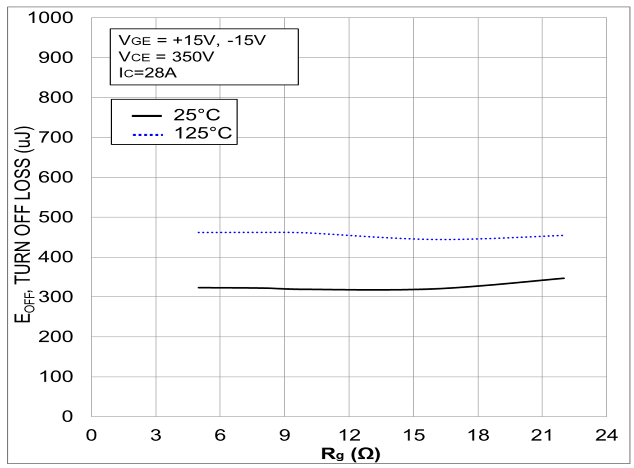


Figure 39. Typical Turn OFF Loss vs. R_G

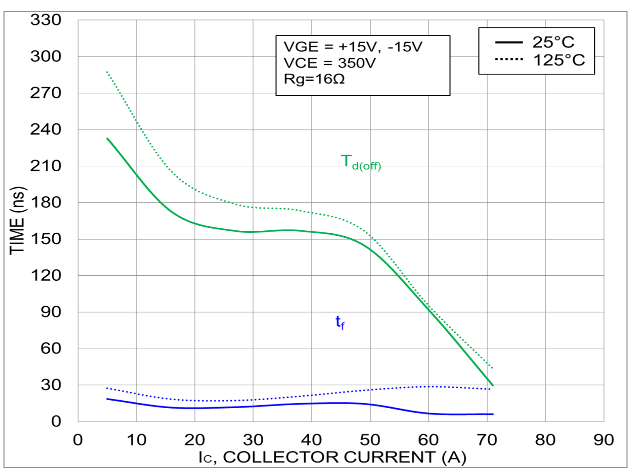


Figure 40. Typical Turn−Off Switching Time vs. I_C

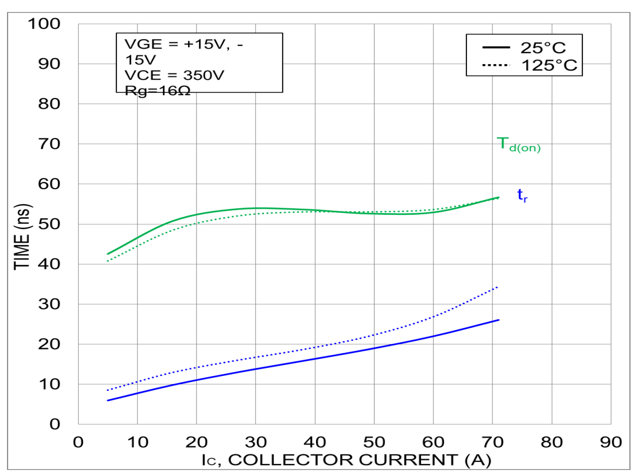


Figure 41. Typical Turn−On Switching Time vs. I_C

TYPICAL CHARACTERISTICS – NEUTRAL POINT IGBT COMMUTATES HALF BRIDGE DIODE

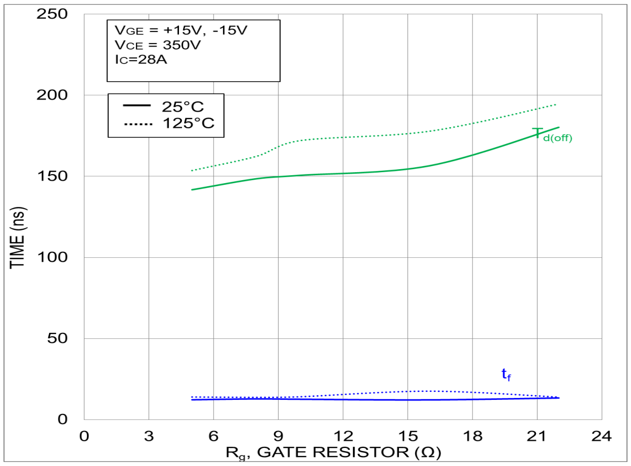


Figure 42. Typical Turn−Off Switching Time vs. R_G

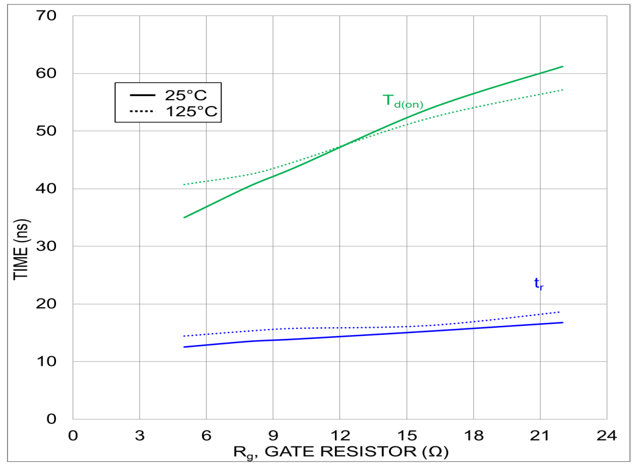


Figure 43. Typical Turn−On Switching Time vs. R_G

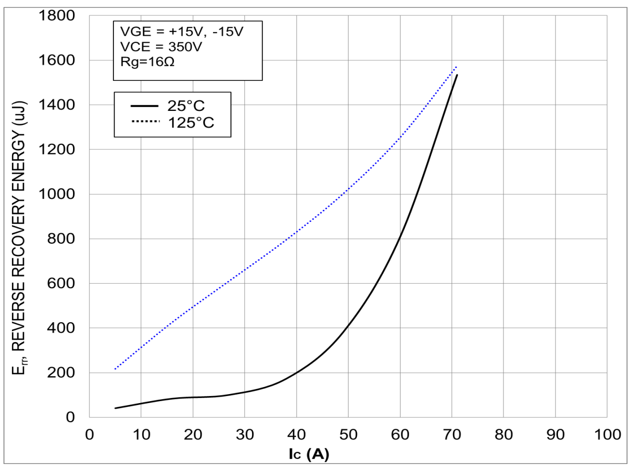


Figure 44. Typical Reverse Recovery Energy Loss vs. I_C

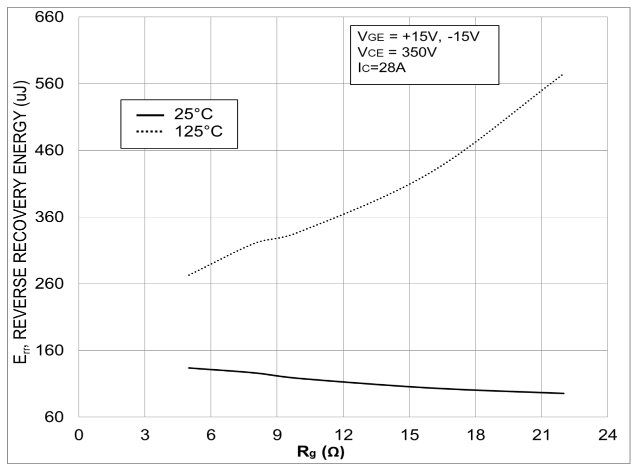


Figure 45. Typical Reverse Recovery Energy Loss vs. R_G

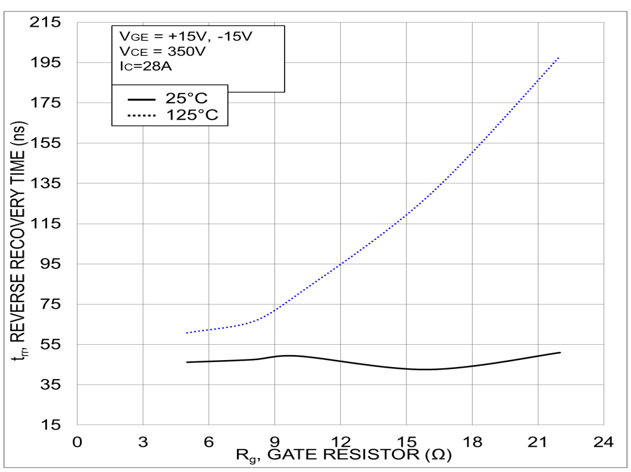


Figure 46. Typical Reverse Recovery Time vs. R_G

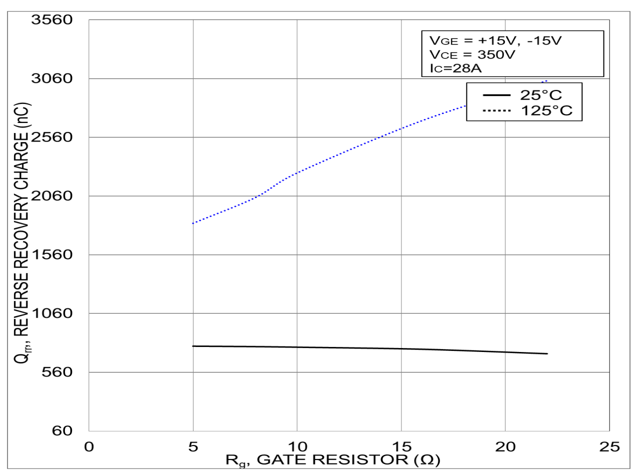


Figure 47. Typical Reverse Recovery Charge vs. R_G

TYPICAL CHARACTERISTICS – NEUTRAL POINT IGBT COMMUTATES HALF BRIDGE DIODE

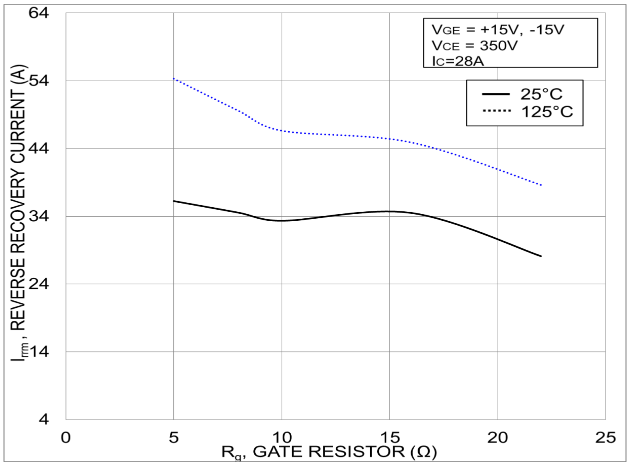


Figure 48. Typical Reverse Recovery Peak Current vs. R_G

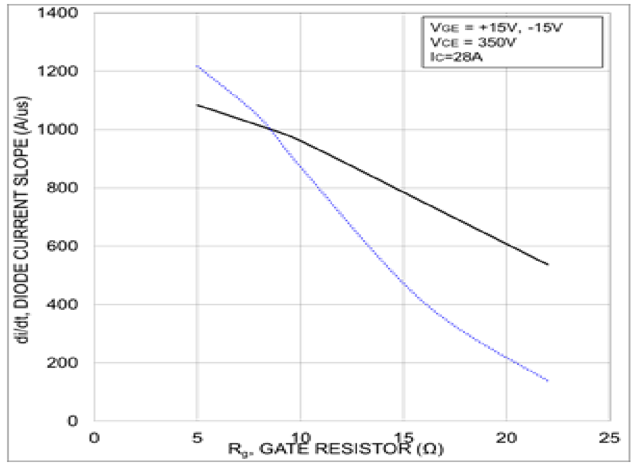


Figure 49. Typical di/dt vs. R_G

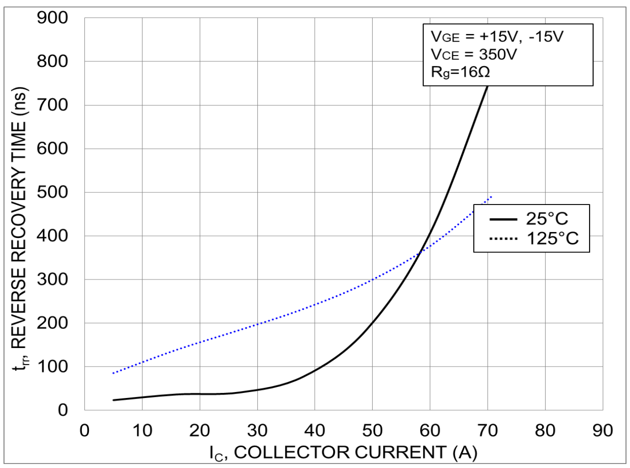


Figure 50. Typical Reverse Recovery Time vs. I_C

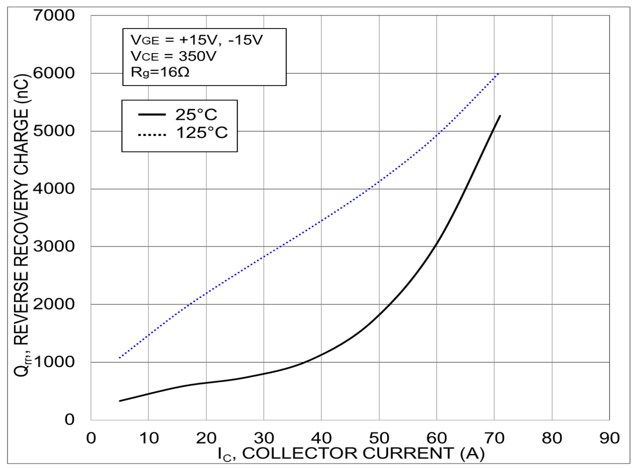


Figure 51. Typical Reverse Recovery Charge vs. I_C

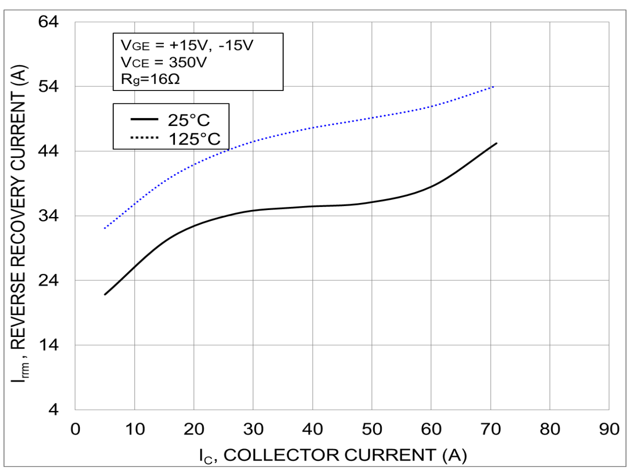


Figure 52. Typical Reverse Recovery Current vs. I_C

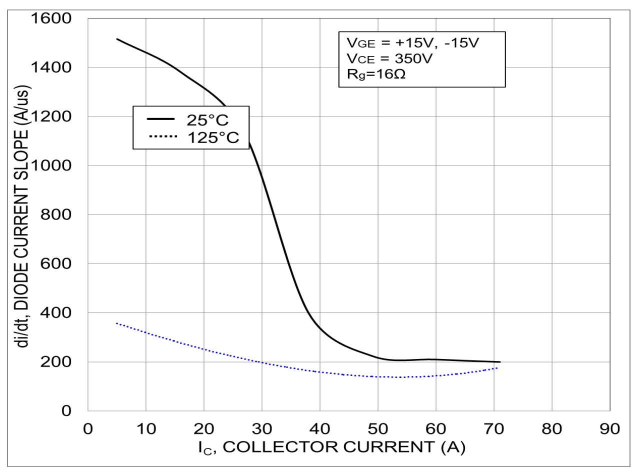
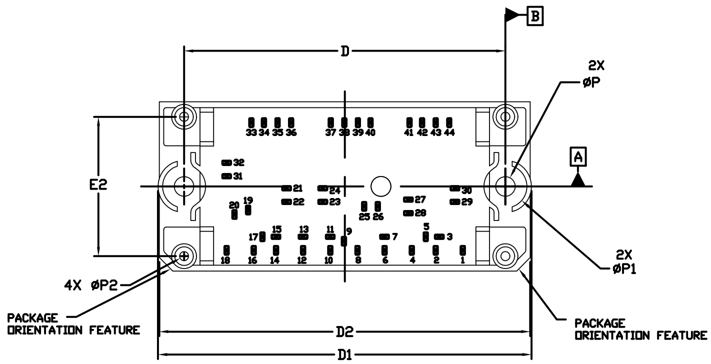


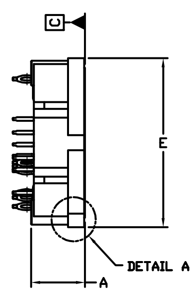
Figure 53. Typical di/dt Current Slope vs. I_C

PIM44, 71x37.4
CASE 180AS
ISSUE O

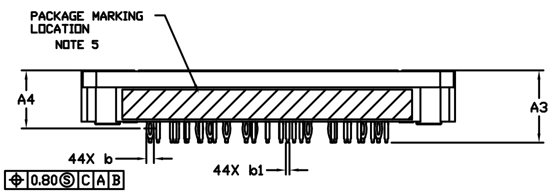
DATE 25 JUN 2018



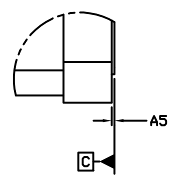
TOP VIEW



END VIEW



SIDE VIEW

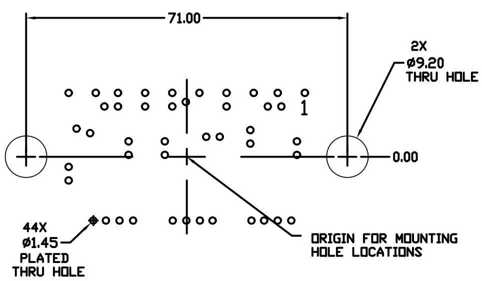


DETAIL A

PIN	PIN POSITION X	PIN POSITION Y	PIN	PIN POSITION X	PIN POSITION Y
1	26.10	14.10	23	−4.85	3.40
2	20.10	14.10	24	−4.85	0.40
3	20.90	11.10	25	4.30	4.40
4	14.80	14.10	26	7.30	4.40
5	17.90	11.10	27	14.05	2.90
6	8.80	14.10	28	14.05	5.90
7	8.80	11.10	29	24.35	3.40
8	2.80	14.10	30	24.35	0.40
9	−0.20	12.10	31	−26.10	−2.25
10	−3.20	14.10	32	−26.10	−5.25
11	−3.20	11.10	33	−20.65	−14.10
12	−9.20	14.10	34	−17.85	−14.10
13	−9.20	11.10	35	−14.85	−14.10
14	−15.20	14.10	36	−11.85	−14.10
15	−15.20	11.10	37	−3.10	−14.10
16	−20.10	14.10	38	−0.10	−14.10
17	−18.20	11.10	39	2.90	−14.10
18	−26.10	14.10	40	5.70	−14.10
19	−21.35	5.20	41	14.30	−14.10
20	−24.35	6.20	42	17.10	−14.10
21	−12.85	0.40	43	20.10	−14.10
22	−12.85	3.40	44	23.10	−14.10

NOTE 4

PIN	PIN POSITION X	PIN POSITION Y	PIN	PIN POSITION X	PIN POSITION Y
1	26.10	−14.10	23	−4.85	−3.40
2	20.10	−14.10	24	−4.85	−0.40
3	20.90	−11.10	25	4.30	−4.40
4	14.80	−14.10	26	7.30	−4.40
5	17.90	−11.10	27	14.05	−2.90
6	8.80	−14.10	28	14.05	−5.90
7	8.80	−11.10	29	24.35	−3.40
8	2.80	−14.10	30	24.35	−0.40
9	−0.20	−12.10	31	−26.10	2.25
10	−3.20	−14.10	32	−26.10	5.25
11	−3.20	−11.10	33	−20.65	14.10
12	−9.20	−14.10	34	−17.85	14.10
13	−9.20	−11.10	35	−14.85	14.10
14	−15.20	−14.10	36	−11.85	14.10
15	−15.20	−11.10	37	−3.10	14.10
16	−20.10	−14.10	38	−0.10	14.10
17	−18.20	−11.10	39	2.90	14.10
18	−26.10	−14.10	40	5.70	14.10
19	−21.35	−5.20	41	14.30	14.10
20	−24.35	−6.20	42	17.10	14.10
21	−12.85	−0.40	43	20.10	14.10
22	−12.85	−3.40	44	23.10	14.10

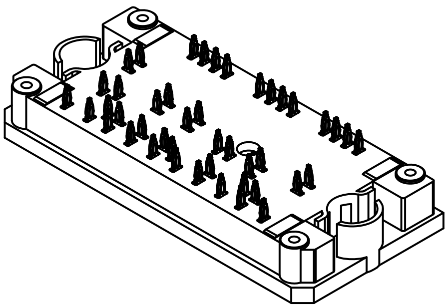


RECOMMENDED
MOUNTING PATTERN

DIM	MILLIMETERS MIN.	NOM.	MAX.
A	11.50	12.00	12.50
A3	15.50	16.00	16.50
A4	12.83 BSC		
A5	0.10	0.20	0.30
b	1.61	1.66	1.71
b1	0.75	0.80	0.85
D	70.50	71.00	71.50
D1	82.00	82.50	83.00
D2	81.50	82.00	82.50
E	36.90	37.40	37.90
E2	30.30	30.80	31.30
P	4.10	4.30	4.50
P1	9.30	9.50	9.70
P2	1.80	2.00	2.20

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS b AND b1 APPLY TO THE PLATED TERMINALS AND ARE MEASURED AT DIMENSION A4.
4. POSITION OF THE CENTER OF THE TERMINALS IS DETERMINED FROM DATUM B THE CENTER OF DIMENSION D, X DIRECTION, AND FROM DATUM A, Y DIRECTION. POSITIONAL TOLERANCE, AS NOTED IN DRAWING, APPLIES TO EACH TERMINAL IN BOTH DIRECTIONS.
5. PACKAGE MARKING IS LOCATED AS SHOWN ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURES.

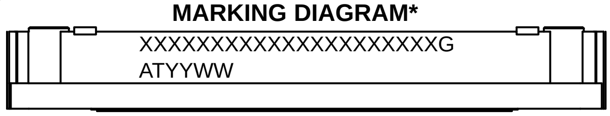
DOCUMENT NUMBER:	98AON92314G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	PIM44, 71x37.4	PAGE 1 OF 2



PIM44, 71x37.4
CASE 180AS
ISSUE O

DATE 15 JUN 2018

GENERIC
MARKING DIAGRAM*



XXXXX = Specific Device Code
G = Pb−Free Package
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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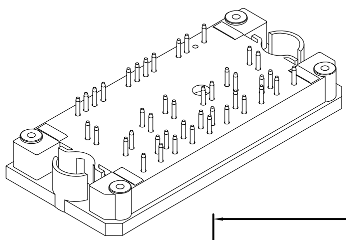
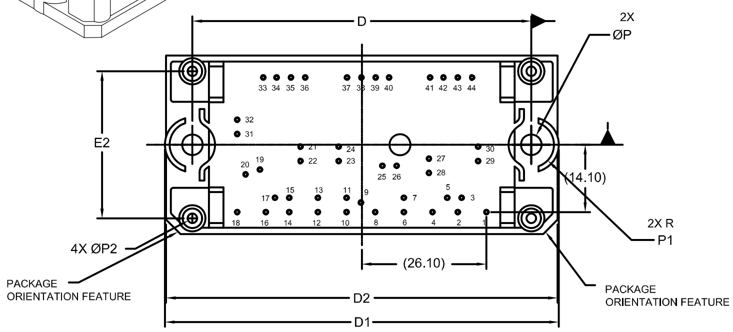
DESCRIPTION:	**PIM44, 71x37.4**	**PAGE 2 OF 2**

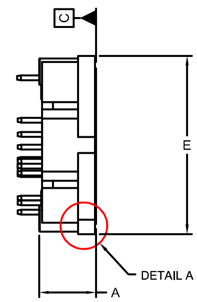


PIM44, 71x37.4 (SOLDER PINS)
CASE 180BN
ISSUE O

DATE 08 OCT 2019

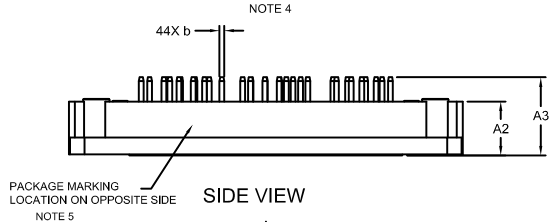


TOP VIEW

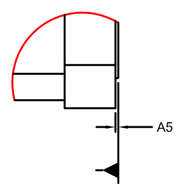


END VIEW

DIM	MILLIMETERS MIN.	NOM.	MAX.
A	11.50	12.00	12.50
A2	10.90	11.40	11.90
A3	15.90	16.40	16.90
A5	0.00	0.30	0.60
b	0.90	1.00	1.10
D	70.50	71.00	71.50
D1	82.00	82.50	83.00
D2	81.50	82.00	82.50
E	36.90	37.40	37.90
E2	30.30	30.80	31.30
P	4.30	4.40	4.50
P1	4.55	4.75	4.95
P2		2.00 REF	



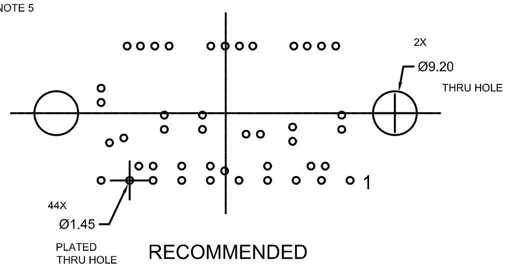
SIDE VIEW



DETAIL A

NOTE 4

PIN	PIN POSITION X	Y	PIN	PIN POSITION X	Y
1	26.10	-14.10	23	-4.85	-3.40
2	20.10	-14.10	24	-4.85	-0.40
3	20.90	-11.10	25	4.30	-4.40
4	14.80	-14.10	26	7.30	-4.40
5	17.90	-11.10	27	14.05	-2.90
6	8.80	-14.10	28	14.05	-5.90
7	8.80	-11.10	29	24.35	-3.40
8	2.80	-14.10	30	24.35	-0.40
9	-0.20	-12.10	31	-26.10	2.25
10	-3.20	-14.10	32	-26.10	5.25
11	-3.20	-11.10	33	-20.65	14.10
12	-9.20	-14.10	34	-17.85	14.10
13	-9.20	-11.10	35	-14.85	14.10
14	-15.20	-14.10	36	-11.85	14.10
15	-15.20	-11.10	37	-3.10	14.10
16	-20.10	-14.10	38	-0.10	14.10
17	-18.20	-11.10	39	2.90	14.10
18	-26.10	-14.10	40	5.70	14.10
19	-21.35	-5.20	41	14.30	14.10
20	-24.35	-6.20	42	17.10	14.10
21	-12.85	-0.40	43	20.10	14.10
22	-12.85	-3.40	44	23.10	14.10

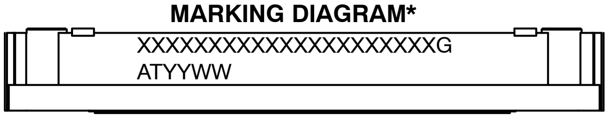


RECOMMENDED
MOUNTING PATTERN*

*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

NOTES:
1. DIMENSIONING AND TOLERANCING PERASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS b APPLIES TO THE PLATED TERMINALS AND IS MEASURED BETWEEN 1.00 AND 3.00 FROM THE TERMINAL TIP.
4. POSITION OF THE CENTER OF THE TERMINALS AND MOUNTING HOLES IS DETERMINED FROM DATUM B THE CENTER OF DIMENSION D, X DIRECTION, AND FROM DATUM A, Y DIRECTION. POSITIONAL TOLERANCE, AS NOTED IN THE DRAWING, APPLIES TO EACH TERMINAL IN BOTH DIRECTIONS.
5. PACKAGE MARKING IS LOCATED AS SHOWN ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURES.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
G = Pb−Free Package
AT = Assembly & Test Site Code
YYWW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	PIM44, 71x37.4 (SOLDER PINS)	PAGE 1 OF 2

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